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# Controlling the Deposition Regime in Close-Proximity Spatial Atomic Layer Deposition with COMSOL®

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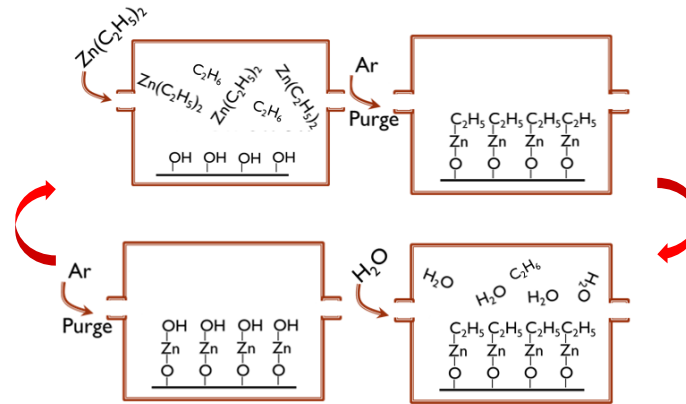
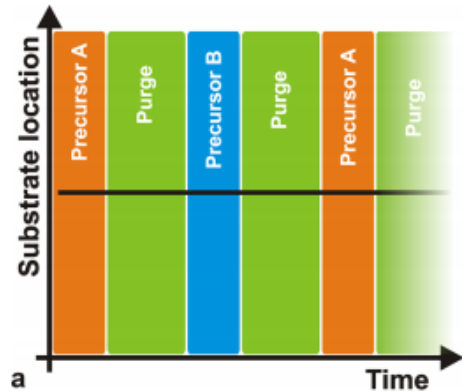
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# Outline

- ✓ Introduction to SALD
- ✓ CFD Comsol Simulation
- ✓ CVD Reaction Rate
- ✓ Experimental Results
- ✓ Conclusions and Future Work

# Introduction to SALD – SALD vs ALD



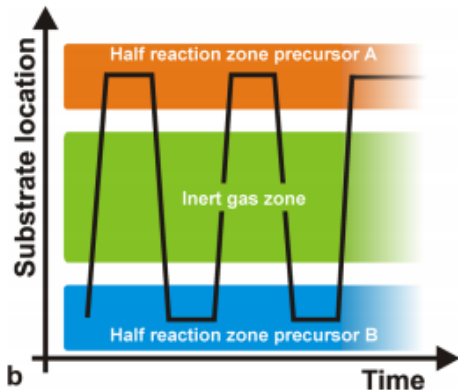
**Vacuum**  
**Slow Process**

**Self-terminating**  
**Surface-limited**

reactions



**Thickness Control**  
**Conformality**  
**Soft Process**

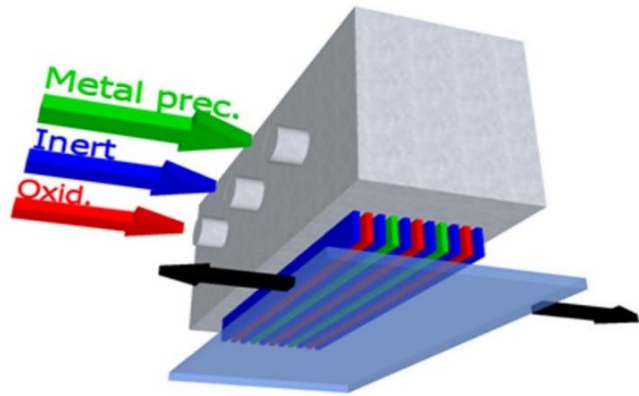


**Atmospheric Pressure**

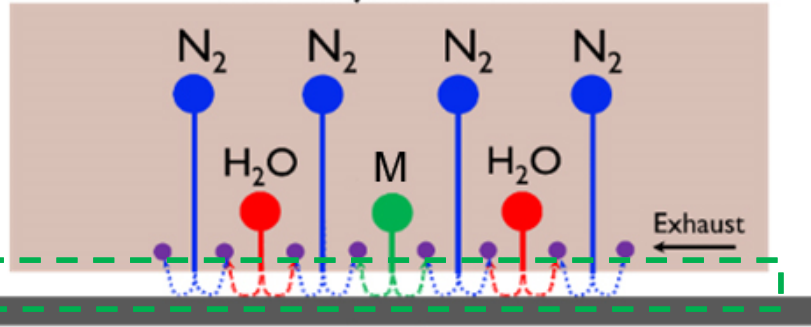
**Up to two orders of magnitude faster than ALD**



# SALD System at LMGP

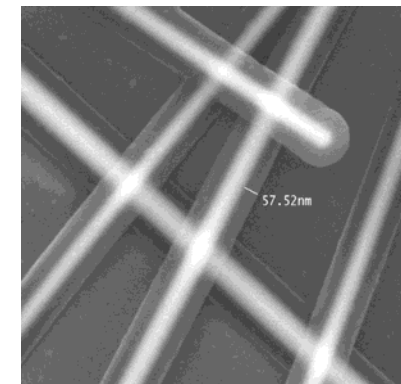
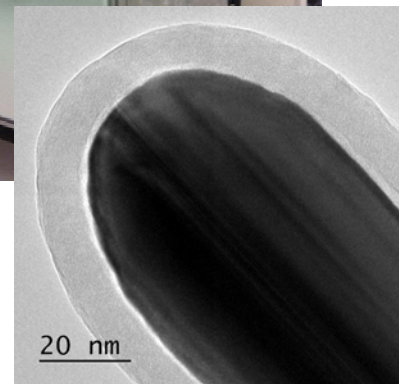
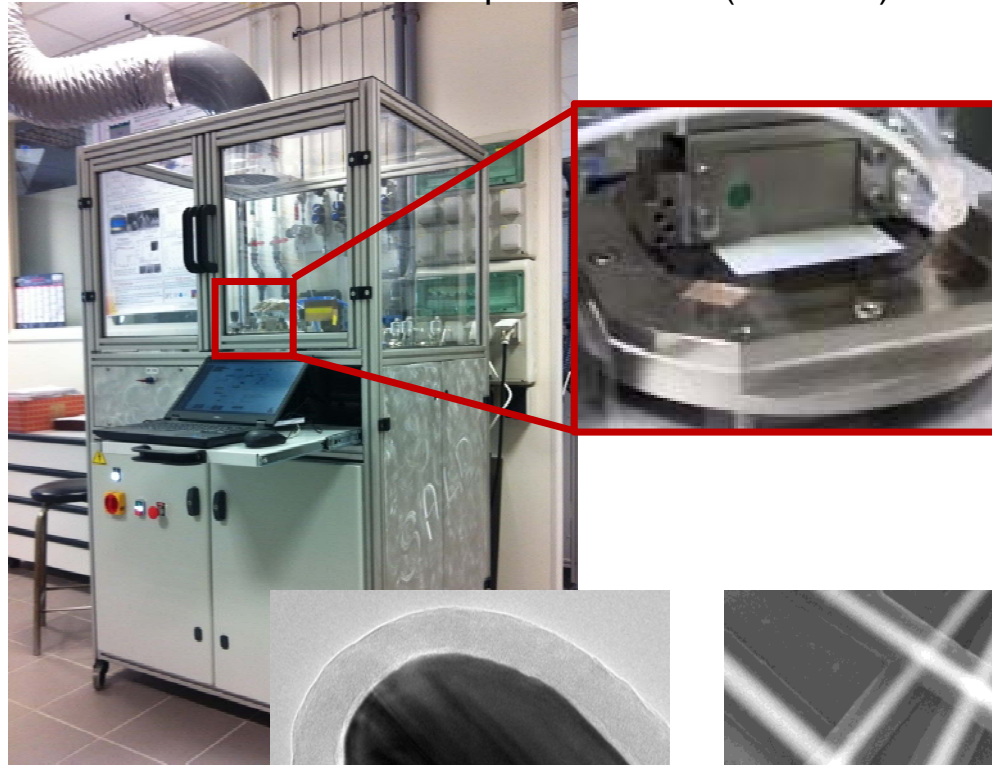


Fixed injection head



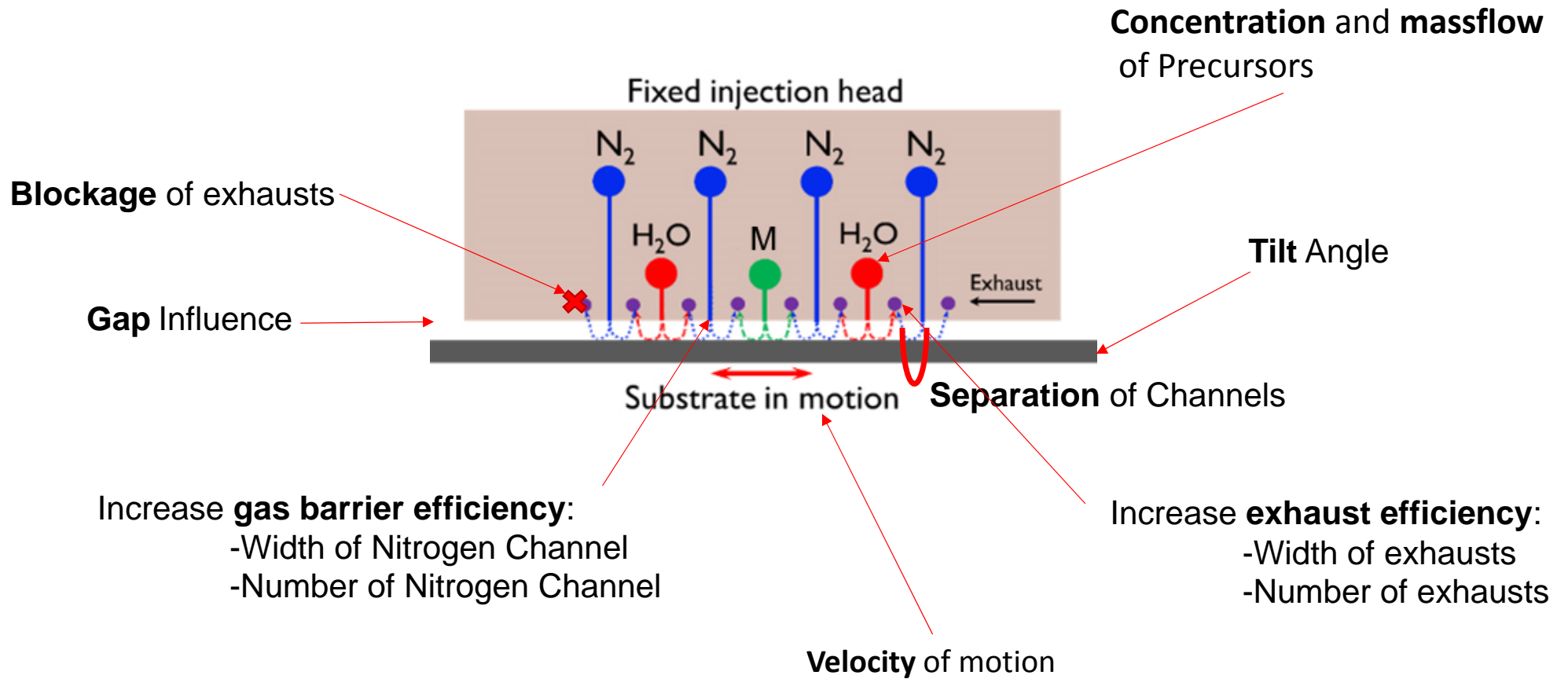
Substrate in motion

In collaboration with Dominique De Barros (STIGMA)



D. Muñoz-Rojas. *Mater. Horiz.*, 2014,1, 314-320

# How to control the growth regime?





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# COMSOL Multiphysics

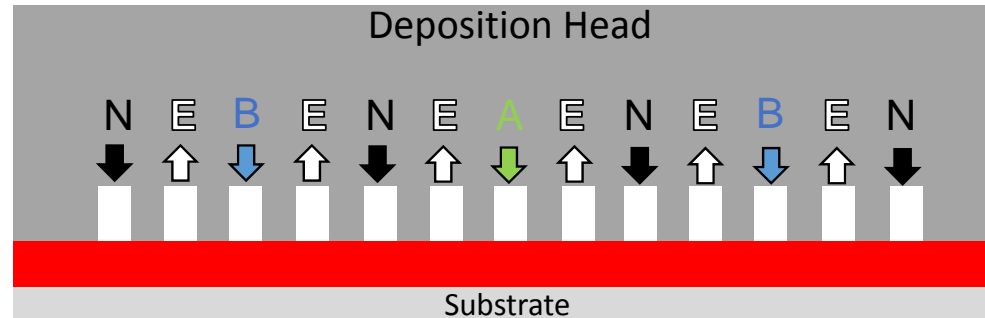
# CFD Simulations for the SALD Close Proximity System

A: ALD Precursor

B: Oxygen Precursor

N: Nitrogen Barrier

E: Exhaust Outlet



**Input Mass Flow**

- 125 SCCM per Inlet

**Diffusion coefficients<sup>1</sup>**

$\sim 10^{-3} \frac{m^2}{s}$

Low Re-number turbulence model

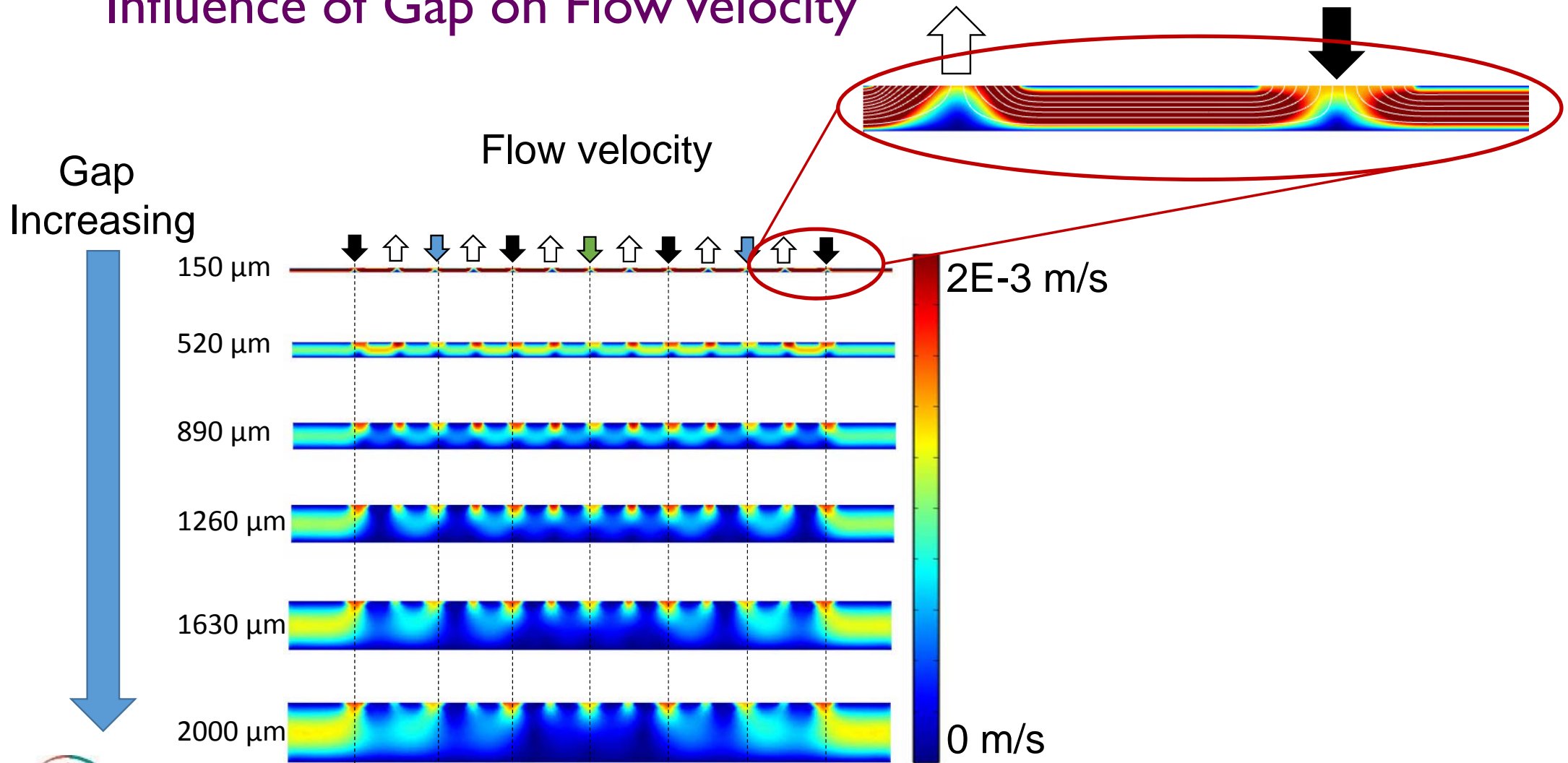
Mass Fraction of each Species

Intermixing of species

ALD ↔ CVD

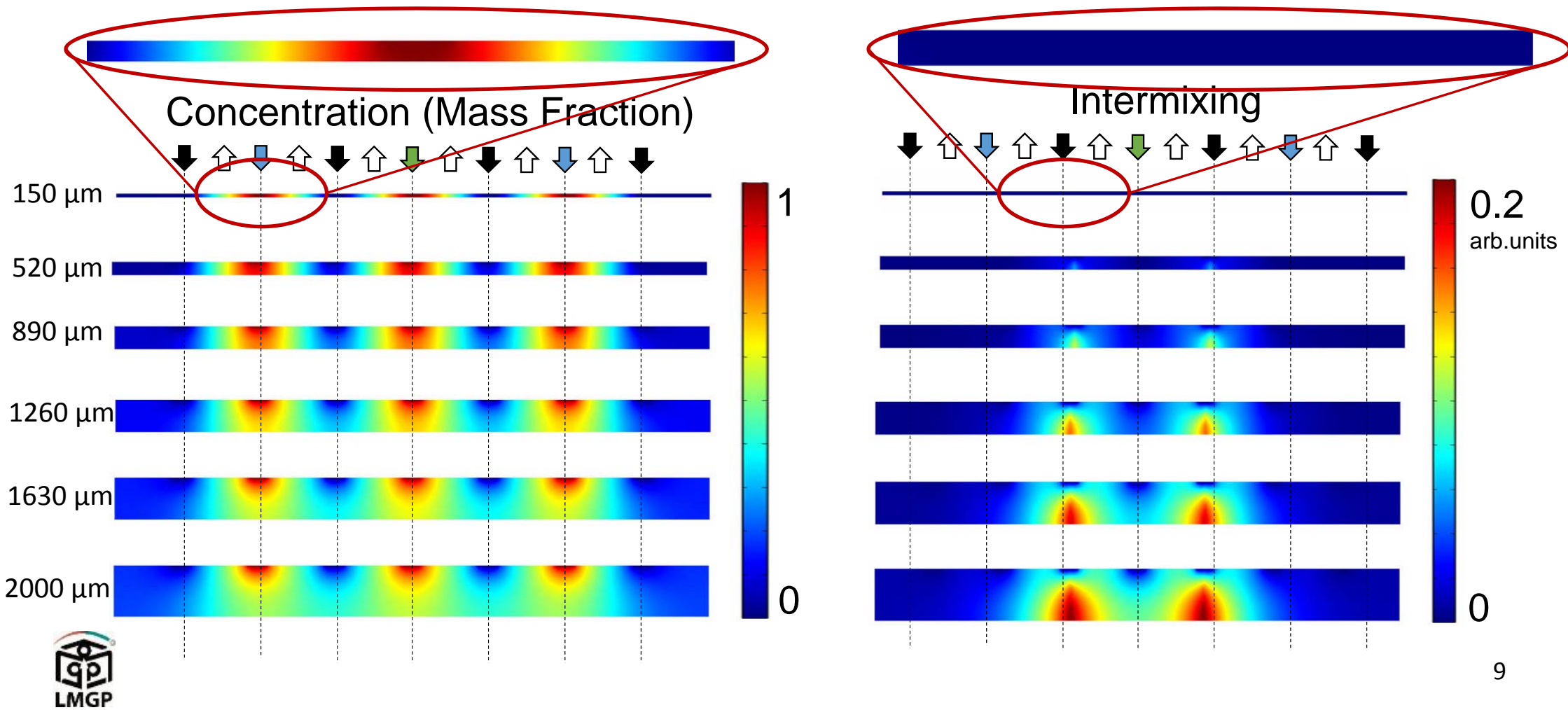
1. J. van Deelen et al. / Surface & Coatings Technology 230 (2013) 239–244

# Influence of Gap on Flow Velocity





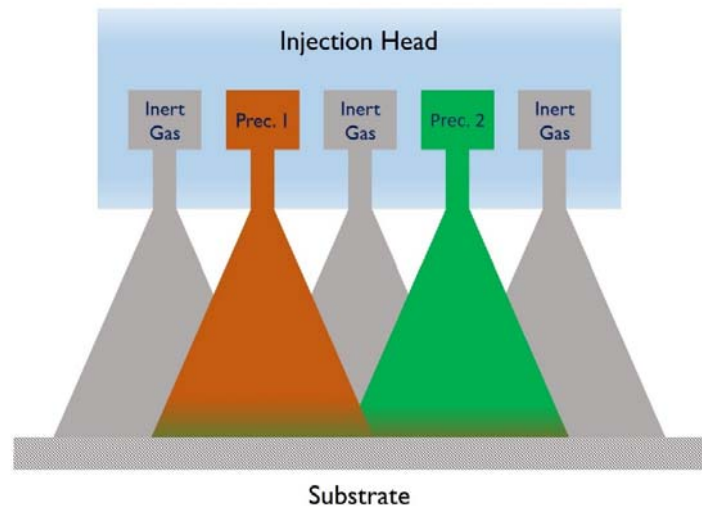
# Gap influence on Concentration and Mixing



# SALD can work on CVD Regime and ALD Regime

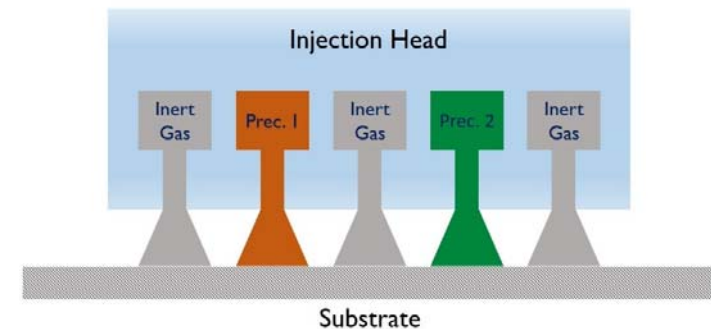
## CVD Regime

- Fast non-self-limited reactions on surface.
- Faster but non-conformal deposition on high aspect ratio
- More difficult to control thickness and homogeneity of film
- Lower film density



## ALD Regime

- Reactions are self-limited.
- Slower deposition but highly homogeneous and conformal.
- Thickness is controlled by the cycles
- Higher film density



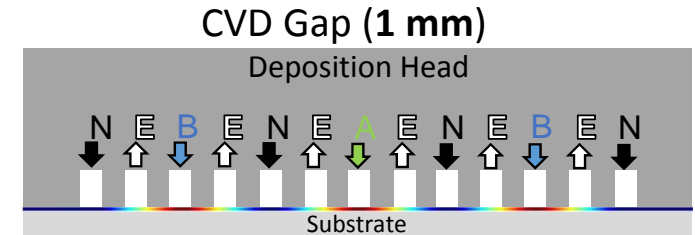
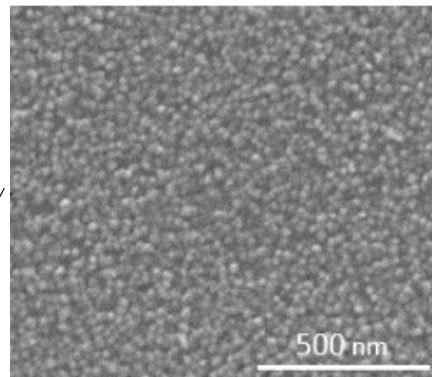
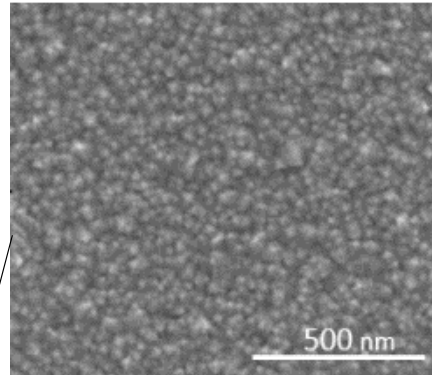
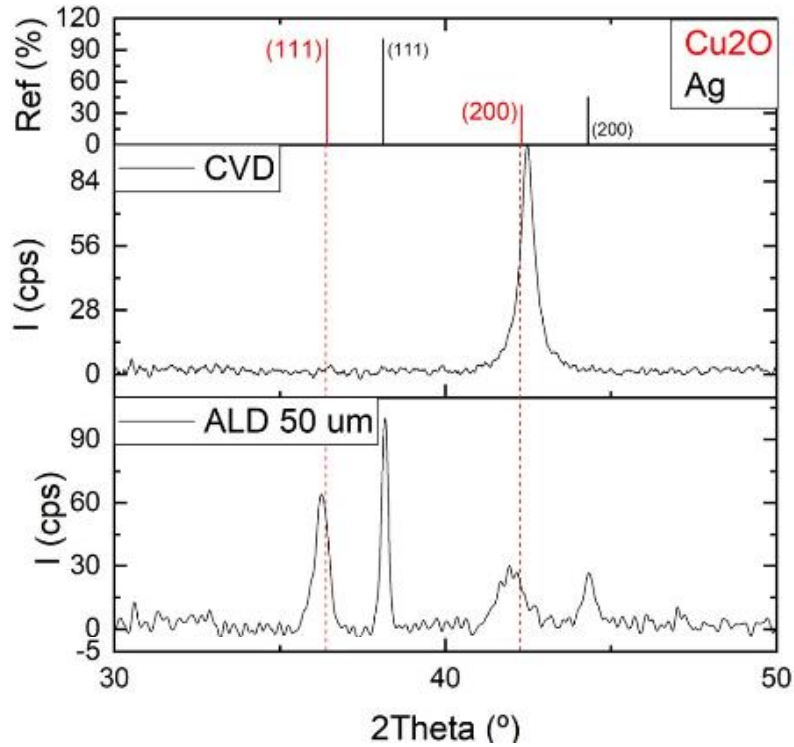


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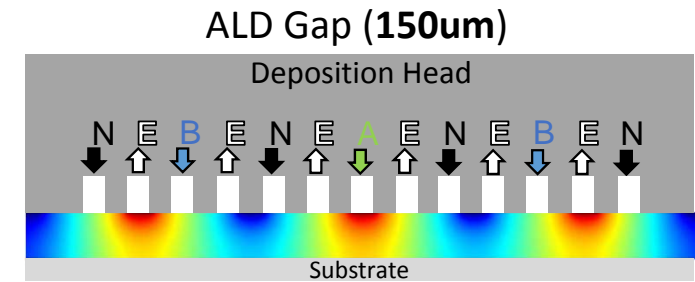


# Comparison with Experimental Results

# Gap Influence – ALD vs CVD mode



Thickness ~ 90 nm  
 33.1 Ohm·cm



Thickness ~ 50 nm  
 $\rho = \sim 9 \text{ Ohm}\cdot\text{cm}$



Cu<sub>2</sub>O on glass

# Conclusions and future work

- Close proximity SALD provides flexibility to switch growth mode: ALD vs CVD

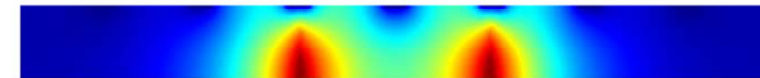
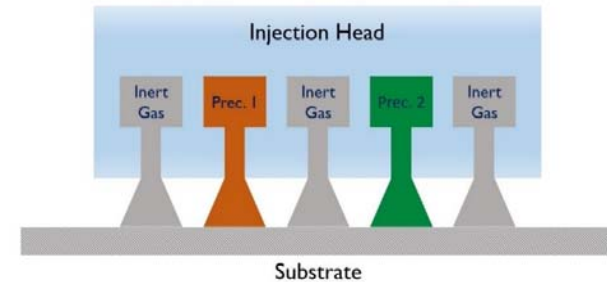
Couple many other parameters of SALD into a general **topography optimization**

- Computational Fluid Dynamics is a powerful tool to simulate and control the many different parameters of SALD.

3D simulation and chemical coupling of film growth and **Growth per Cycle** determination

- Correlate gap values and intermixing to physical properties of the deposited film.

Correlation between chemistry kinetics and experimental film depositions





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# Thanks you for your attention

César MASSE

I acknowledge and thank CONACYT for funding my research at LMGP.